

MPEG AUDIO CLOCK SOURCE

MK1413

Description

The MK1413 is the ideal way to generate clocks for MPEG audio devices in computers. The device uses IDT's proprietary mixture of analog and digital Phase-Locked Loop (PLL) technology to synthesize one of four frequencies from the 14.31818 MHz reference. In an 8-pin SOIC, the MK1413 can save component count, board space, and cost over crystals and oscillators, and increase reliability by eliminating three expensive mechanical devices from the board.

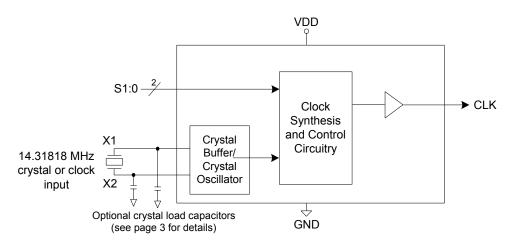
IDT offers many other clocks for computers and computer peripherals. Consult IDT when you need to remove crystals and oscillators from your board.

Features

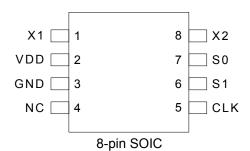
- Packaged in 8-pin SOIC
- · Available in Pb (lead) free package
- Input crystal or clock frequency of 14.31818 MHz
- Provides master MPEG clocks for 32 kHz, 44.1 kHz, and 48 kHz sampling rates
- Output clock frequencies of 8.192 MHz, 11.2896 MHz, 12.288 MHz, and 16.9344 MHz
- · Low jitter
- 25 mA drive capability at TTL levels (at 5.0 V)
- 3.3 V or 5.0 V (±10%) supply voltage
- Advanced, low-power CMOS process

NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

Block Diagram



Pin Assignment



Audio Clock Output Selection Table

| S1 | S0 | Audio Clock (pin 5) | Accuracy (ppm) |
|----|----|---------------------|----------------|
| 0 | 0 | 8.192 MHz | -2 ppm |
| 0 | 1 | 11.2896 MHz | -24 ppm |
| 1 | 0 | 12.288 MHz | -2 ppm |
| 1 | 1 | 16.9344 MHz | -24 ppm |

Pin Descriptions

| Pin Number | Pin Name | Pin Type | Pin Description | | | |
|---------------|-------------|-------------|--|--|--|--|
| 1 | X1 | Input | Crystal connection. Connect this pin to a 14.31818 MHz crystal or clock. | | | |
| 2 | VDD | Power | Connect to 3.3 V or 5 V. | | | |
| 3 | GND | Power | Connect to ground. | | | |
| 4 | NC | _ | No connect. | | | |
| 5 | CLK | Output | Audio clock output as per table above. | | | |
| 6 | S1 | Input | Frequency Select 1 input. Determines CLK output as per table above. | | | |
| 7 | S0 | Input | Frequency Select 0 input. Determines CLK output as per table above. | | | |
| 8 | X2 | Output | Crystal connection to a 14.31818 MHz crystal or leave unconnected for clock input. | | | |

Application Information

Series Termination Resistor

Clock output traces should use series termination. For series terminating a 50Ω trace (a commonly used trace impedance), place a 33Ω resistor in series with the clock line and as close to the clock output pin as possible. The nominal impedance of the clock output is 20Ω

Crystal Load Capacitors

The device crystal connections should include pads for capacitors from X1 to ground and from X2 to ground, and a parallel rsonant 14.31818 MHz crystal is recommended. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance. To reduce possible noise pickup, use very short PCB traces (and no vias) been the crystal and device.

The value (in pF) of each crystal load capacitor should equal (C_L -4) x2, where C_L is the crystal's load (correlation) capacitance in pF. The frequency tolerance of the crystal should be 50 ppm or better.For a clock input, connect X1 and leave X2 unconnected. Because these capacitors adjust the stray capacitance of the PCB, check the output frequency using your final layout to see if the value of C should be changed.

PCB Layout Recommendations

Observe the following guidelines for optimum device

performance and lowest output phase noise:

- 1) Each 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.
- 2) The external crystal should be mounted next to the device with short traces. The X1 and X2 traces should not be routed next to each other with minimum spaces, instead they should be separated and away from other traces.
- 3) To minimize EMI, and obtain the best signal integrity, the 33Ω series termination resistor should be placed close to the clock output.
- 4) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers (the ferrite bead and bulk decoupling capacitor can be mounted on the back). Other signal traces should be routed away from the MK1413. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK1413. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

| Item | Rating |
|---|---------------------|
| Supply Voltage, VDD | 7 V |
| All Inputs and Outputs | -0.5 V to VDD+0.5 V |
| Ambient Operating Temperature | 0 to +70° C |
| Storage Temperature | -65 to +150° C |
| Junction Temperature | 125° C |
| Soldering Temperature (max of 10 seconds) | 260° C |

Recommended Operation Conditions

| Parameter | Min. | Тур. | Max. | Units |
|---|------|------|------|-------|
| Ambient Operating Temperature | 0 | | +70 | °C |
| Power Supply Voltage (measured in respect to GND) | +3.0 | | +5.5 | V |

DC Electrical Characteristics

Unless stated otherwise, **VDD** = **5.0 V** ±**10%**, Ambient Temperature 0 to +70° C

| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Units |
|----------------------------|-----------------|--------------------------|-----------|-------|-----------|-------|
| Operating Voltage | VDD | | 3.0 | | 5.5 | V |
| Input High Voltage | V _{IH} | input clock only | (VDD/2)+1 | VDD/2 | | V |
| Input Low Voltage | V _{IL} | input clock only | | VDD/2 | (VDD/2)-1 | V |
| Output High Voltage | V _{OH} | $I_{OH} = -4 \text{ mA}$ | VDD-0.4 | | | V |
| Output High Voltage | V _{OH} | I _{OH} = -25 mA | 2.4 | | | V |
| Output Low Voltage | V _{OL} | I _{OL} = 25 mA | | | 0.4 | V |
| Supply Current | IDD | 5 V, no Load | | 12 | | mA |
| Supply Current | IDD | 3.3 V, no Load | | 7 | | mA |
| Input Capacitance | C _{IN} | S0, S1 pins | | 7 | | pF |
| Synthesize Frequency Error | | With exact crystal | | | 25 | ppm |

AC Electrical Characteristics

Unless stated otherwise, **VDD = 5.0 V \pm 10\%**, Ambient Temperature 0 to $+70^{\circ}$ C

| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Units |
|-------------------------------------|-----------------|------------------|------|----------|------|-------|
| Input Clock or Crystal Frequency | | | | 14.31818 | | MHz |
| Input Crystal Accuracy | | | | | 50 | ppm |
| Input Clock Duty Cycle | | Time above VDD/2 | 20 | | 80 | % |
| Output Clock Rise Time | t _{OR} | 0.8 to 2.0 V | | | 1.5 | ns |
| Output Clock Fall Time | t _{OF} | 2.0 to 0.8 V | | | 1.5 | ns |
| Output Clock Duty Cycle | | Time above VDD/2 | 40 | 50 | 60 | % |
| Absolute Clock Period Jitter | | | | 200 | | ps |
| One Sigma, Clock Period Jitter | | | | 70 | | ps |

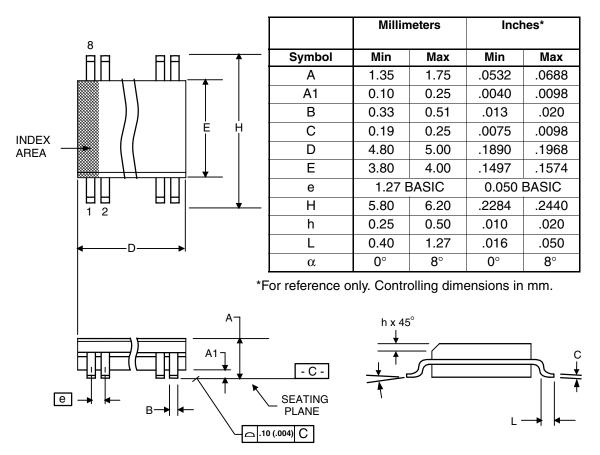
Note: Typical values are at 25°C

Thermal Characteristics

| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Units |
|-------------------------------------|---------------|----------------|------|------|------|-------|
| Thermal Resistance Junction to | θ_{JA} | Still air | | 150 | | ° C/W |
| Ambient | θ_{JA} | 1 m/s air flow | | 140 | | ° C/W |
| | θ_{JA} | 3 m/s air flow | | 120 | | ° C/W |
| Thermal Resistance Junction to Case | θ_{JC} | | | 40 | | ° C/W |

Package Outline and Package Dimensions (8-pin SOIC, 150 mil Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

| Part / Order Number | Marking | Shipping Packaging | Package | Temperature |
|---------------------|----------|--------------------|------------|-------------|
| MK1413S* | MK1413S | Tubes | 8-pin SOIC | 0 to +70° C |
| MK1413STR* | MK1413S | Tape and Reel | 8-pin SOIC | 0 to +70° C |
| MK1413SLF | MK1413SL | Tubes | 8-pin SOIC | 0 to +70° C |
| MK1413SLFTR | MK1413SL | Tape and Reel | 8-pin SOIC | 0 to +70° C |

*NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

Parts that are ordered with a "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

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